

ABSTRACT OF THE DISCLOSURE

The present invention comprises a first main face (22a) on a surface side of a substrate (21a). An island portion (26) 5 is formed on the first main face (22a) and a semiconductor chip (29), etc. are adhered thereto. The semiconductor chip (29), etc. are sealed in the hollow portion that is constructed by a column portion (23) and a transparent glass plate (36). Then, the column portion (23) and the transparent glass plate (36) 10 are adhered by epoxy resin, or the like.

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